

## SPH3 Product Family Overview

### High Density, High Performance Connectors

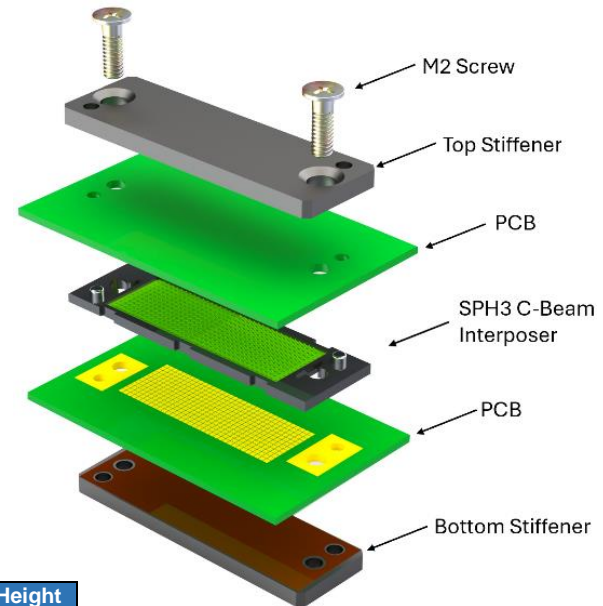
#### OVERVIEW

Utilizing C-Beam™ technology, the SPH3 family of standard connectors are designed for high performance Board-to-Board (BtB) and Flex-to-Board (FtB) applications. The large pin counts enable combining numerous high speed differential pairs, high power, and signals in one connector. Compatible hardware is available with screw retention for simple assembly into the host system. Neoconix can also provide complete turnkey assemblies that include a high performance FPC.



#### FEATURES

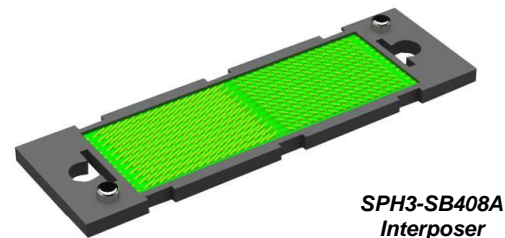
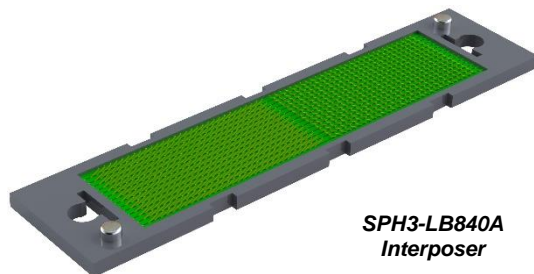
- High Performance C-Beam™ Connector Technology
- High speed to 112 Gbps
- Product options at 0.50 and 0.60mm pitch
- Standardized 1.1 mm interposer thickness
- 3 Form Factors – Small(S), Medium(M) & Large(L)
- High-temperature thermoplastic housing
- Integrated Alignment Posts
- Maximized pin count per form factor
- Current capacity up to 0.75A per position
- Standard assembly hardware available
- Compliant with ROHS 2011/65/EU and IPC-4101B (halogen-free)



#### STANDARD PRODUCT FAMILY<sup>1</sup>

Interposer Part Number	Pitch (mm)	Form Factor	Pin Count	Rows	Cols	Length (mm)	Width (mm)	Height (mm)
SPH3-SB408A	0.6	S	408	12	34	31.8	9.6	1.1
SPH3-MB480A		M	480	12	40	35.7		
SPH3-LB600A		L	600	12	50	41.9		
SPH3-SB560A	0.5	S	560	14	40	31.8		
SPH3-MB672A		M	672	14	48	35.7		
SPH3-LB840A		L	840	14	60	41.9		

1. Consult Neoconix for availability



#### FOR MORE INFORMATION

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